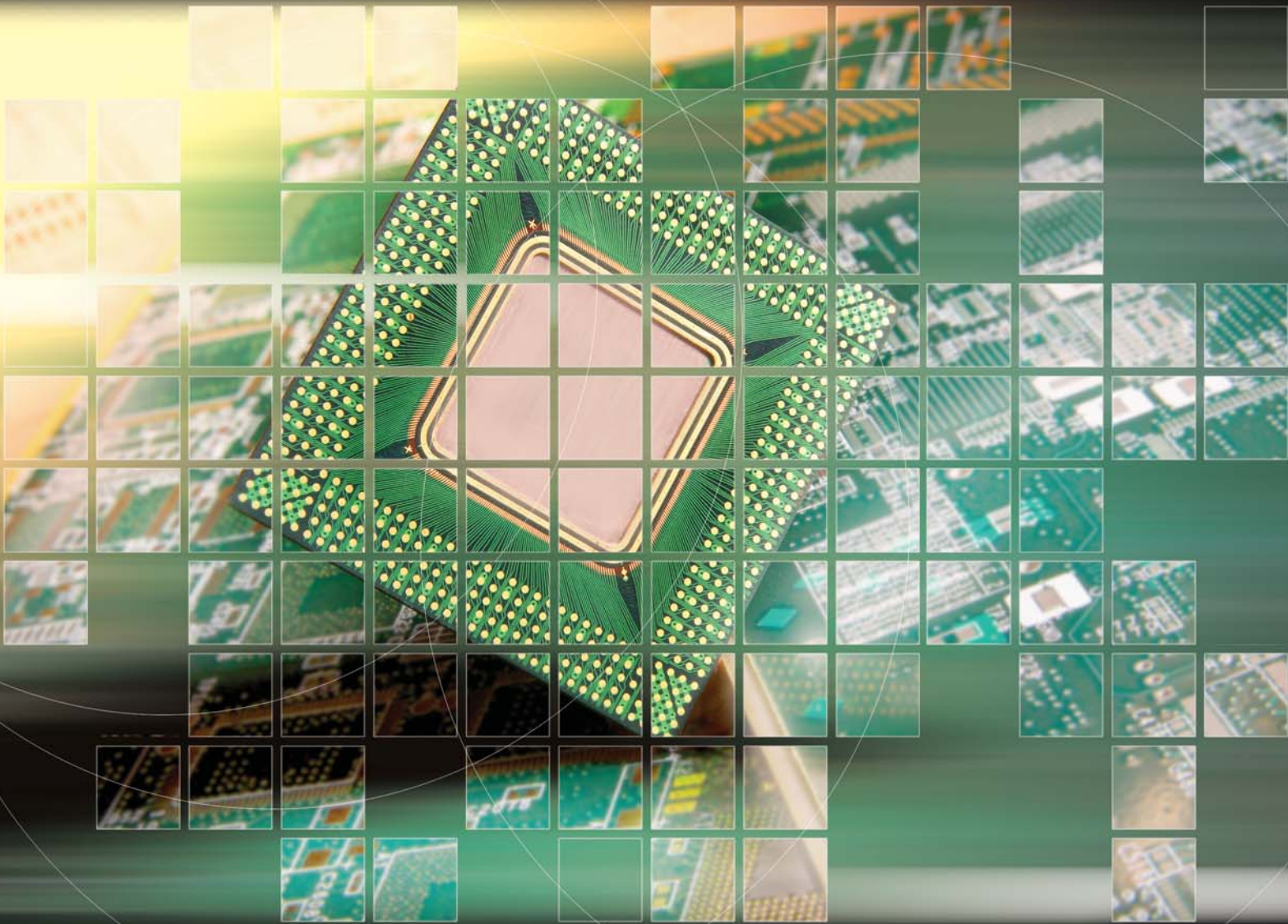


MICROVIAS & FINE LINES

BLIND • BURIED • LASER DRILLED • 25 MICRONS



Compunetics is one of the few PCB manufacturers in the world to make these versatile boards for specialized applications and unusual physical constraints.

compunetics
excellence, measured in microns.

Compunetics is the vendor of choice when requirements include very high density interconnects.

Microvia specifications:

- Laser microvias as small as 1 mil (25 µm)
- In-house YAG laser
- Mechanical drilled
- Stacked and stepped microvias

Fine lines:

Compunetics is a pioneer in very high density circuitry. Fine lines are produced using the latest generation photoresist resulting in circuits as small as 1 mil (25 µm).

Compunetics microvias and fine line circuitry is the perfect fit for applications including:

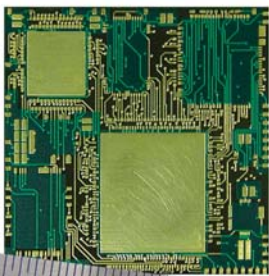
- Supercomputing
- Military
- Medical
- Telecommunications
- Chip packaging
- High density flex connectors

Stacked Microvias

Sequential build: 3 layers RCC both sides.

Specifications

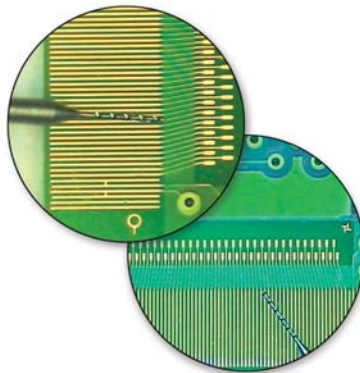
- Layers: 8
 Trace/Space: 2/3 (50/75 µm)
 Blind Microvias
 Stacked Microvias
 Sequential Build
 3 Layers RCC top & bottom
 Finish: Electrolytic Ni/Au



Fine Line

Specifications

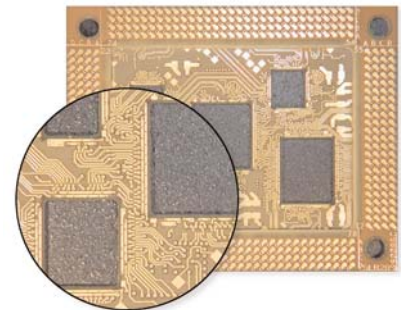
- Layers: 4
 Trace/Space: 1.5/1.5 (35/35 µm)
 Finish: Electrolytic Ni/Au
 Thickness: 31 ± 1 mils



High Layer Fine Line

Specifications

- Layers: 14
 Trace/Space: 2/2 (50/50 µm)
 Finish: Electrolytic Gold
 Blind Vias
 Cavity Design
 2 Buried Resistor Layers



MICROVIAS

Stacked Microvias • Buried Microvias • Stepped Microvias • Thru Microvias

